

Product Highlight

Features

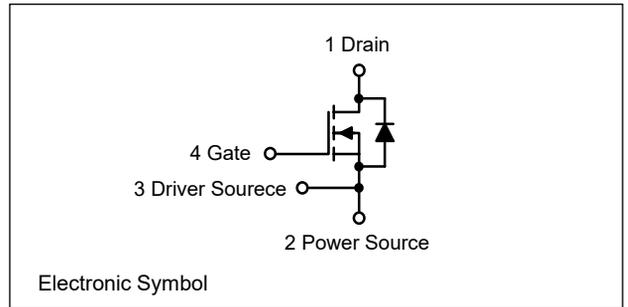
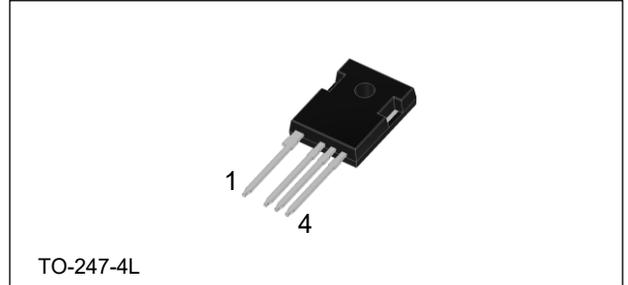
- High switching speed with a low gate charge
- Fast intrinsic diode with low reverse recovery
- Robust Avalanche Capability
- 100% Avalanche Tested
- Pb-free, Halogen Free, and RoHS Compliant

Benefits

- System efficiency improvement
- Higher frequency applicability
- Increased power density
- Reduced cooling effort

Applications

- Solar inverter
- EV charging station
- UPS
- Industrial power supply



Key Parameters

$BV_{DSS, T_C=25^\circ C}$	$I_{D, T_C=25^\circ C}$	$R_{DS(on), typ}$	$Q_{g, typ}$
1200 V	57 A	40 mΩ	62 nC



Package Marking and Ordering Information

Part Number	Top Marking	Package	Packing Method	Quantity
MSQS120R040T2TH	120R040T2	TO-247-4L	Tube	30 units

Absolute Maximum Ratings ($T_C = 25^\circ C$ unless otherwise noted)

Symbol	Parameter	Value	Unit
V_{DSS}	Drain to Source Voltage	1200	V
V_{GS}	Gate to Source Voltage (DC)	-10 / +22	V
V_{GSop}	Recommended Operation Value	-5...-3 / +18	V
I_D	Drain Current	Continuous ($T_C = 25^\circ C$)	57*
		Continuous ($T_C = 100^\circ C$)	40*
I_{DM}	Drain Current	Pulsed (Note1)	142*
P_D	Power Dissipation	($T_C = 25^\circ C$)	288
		Derate Above 25°C	1.9
T_J	Operating Temperature Range	-55 to 175	°C

*Limited by maximum junction temperature.

Note 1. Repetitive rating: pulse-width limited by maximum junction temperature.

1. Package

Temperature Ratings

Symbol	Parameter	Value	Unit
T_{STG}	Storage Temperature Range	-55 to 175	°C
T_L	Maximum Lead Temperature for Soldering, 1/8" from Case for 10 Seconds	260	°C

Thermal Characteristics

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.52	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	40	



2. MOSFET

Electrical Characteristics ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
Off Characteristics						
BV_{DSS}	Drain to Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 1\text{ mA}$	1200			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 1200\text{ V}, V_{GS} = 0\text{ V}$		1	100	μA
		$V_{DS} = 1200\text{ V}, V_{GS} = 0\text{ V}, T_J = 175^\circ\text{C}$		10		
I_{GSS}	Gate-Source Leakage Current	$V_{GS} = +22\text{ V}, V_{DS} = 0\text{ V}$			+100	nA
		$V_{GS} = -10\text{ V}, V_{DS} = 0\text{ V}$			-100	
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 10\text{ mA}$ (tested after $V_{GS} = 22\text{ V}, 1\text{ ms pulse}$)	2.0	3.0	4.5	V
$R_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 18\text{ V}, I_D = 28\text{ A}$		40.0	56.0	m Ω
		$V_{GS} = 18\text{ V}, I_D = 28\text{ A}, T_J = 175^\circ\text{C}$		64.0		
		$V_{GS} = 15\text{ V}, I_D = 28\text{ A}$		55.5		
g_{fs}	Transconductance	$V_{DS} = 20\text{ V}, I_D = 28\text{ A}$		16.9		S
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS} = 800\text{ V}, V_{GS} = 0\text{ V}, f = 250\text{ kHz}$		1668		μF
C_{oss}	Output Capacitance			105		
C_{rss}	Reverse Capacitance			4		
E_{oss}	Stored Energy in Output Capacitance	$V_{DS} = 0\text{ V to } 800\text{ V}, V_{GS} = 0\text{ V}$		42		μJ
$C_{o(er)}$	Energy Related Output Capacitance			132		μF
$C_{o(tr)}$	Time Related Output Capacitance			201		
$Q_{g(tot)}$	Total Gate Charge	$V_{DS} = 800\text{ V}, I_D = 28\text{ A},$ $V_{GS} = -3\text{ V} / 18\text{ V},$ Inductive load		62		nC
Q_{gs}	Gate to Source Charge			20		
Q_{gd}	Gate to Drain "Miller" Charge			14		
R_G	Internal Gate Resistance	$f = 1\text{ MHz}, V_{AC} = 30\text{ mV}$		3.0		Ω
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	$V_{DS} = 800\text{ V}, I_D = 28\text{ A},$ $V_{GS} = -3\text{ V} / 18\text{ V}, R_G = 6.8\ \Omega,$ Inductive load		19		ns
t_r	Turn-On Rise Time			15		
$t_{d(off)}$	Turn-Off Delay Time			35		
t_f	Turn-Off Fall Time			8		
E_{on}	Turn-on Switching Energy			158		μJ
E_{off}	Turn-off Switching Energy			100		
E_{tot}	Total Switching Energy			258		

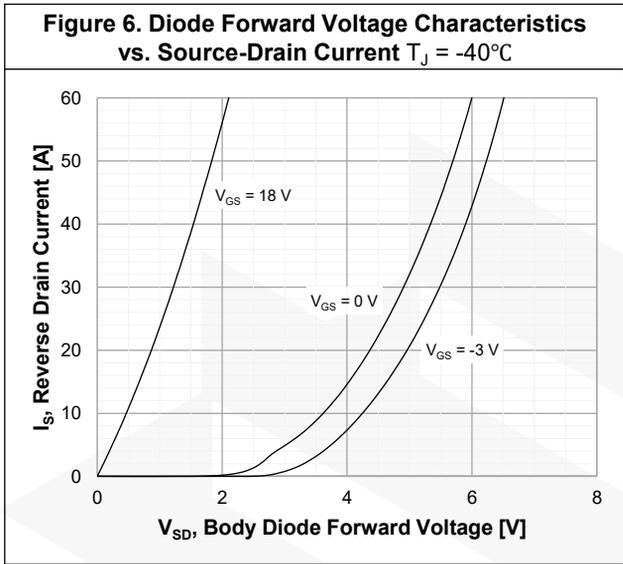
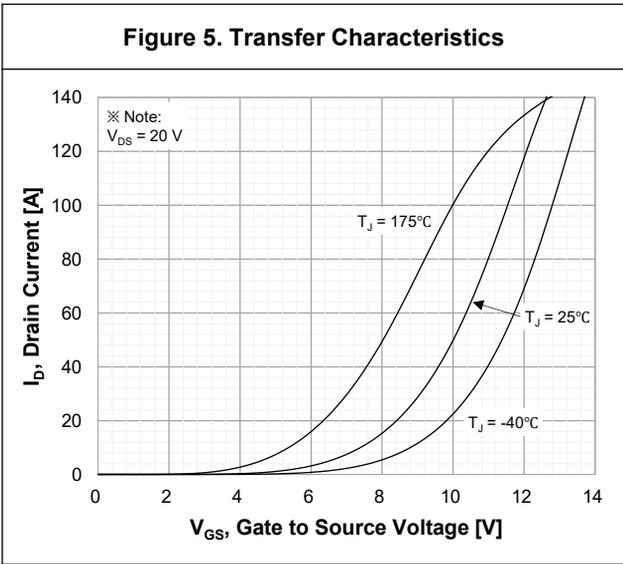
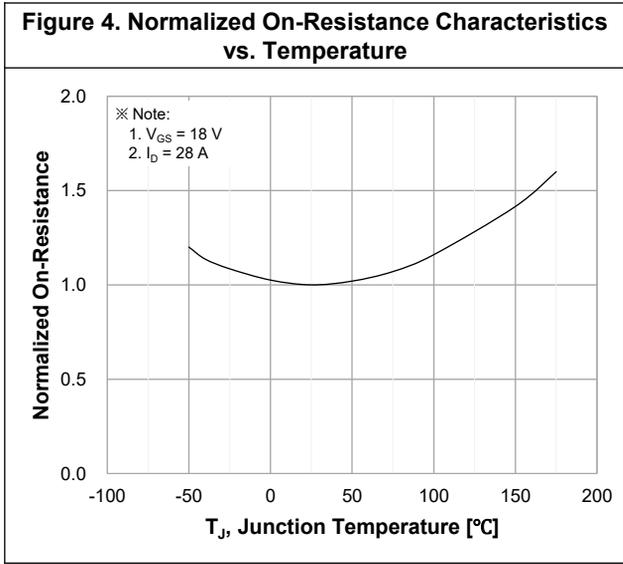
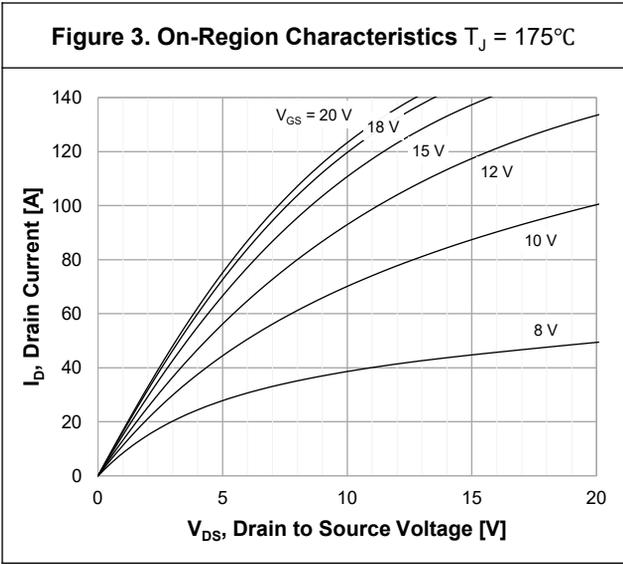
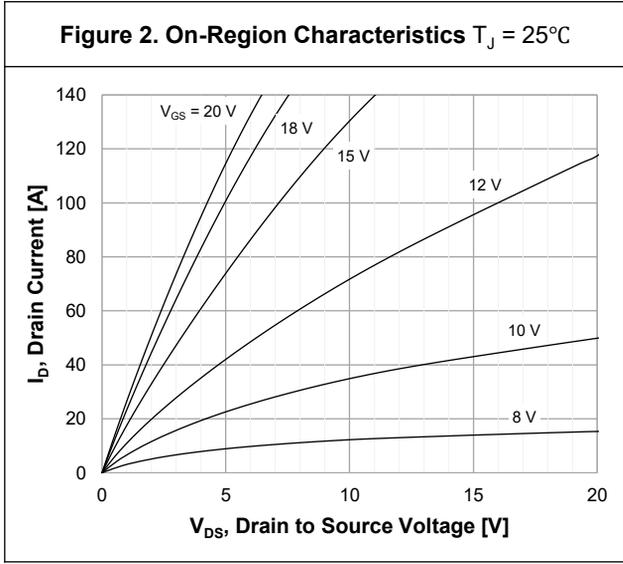
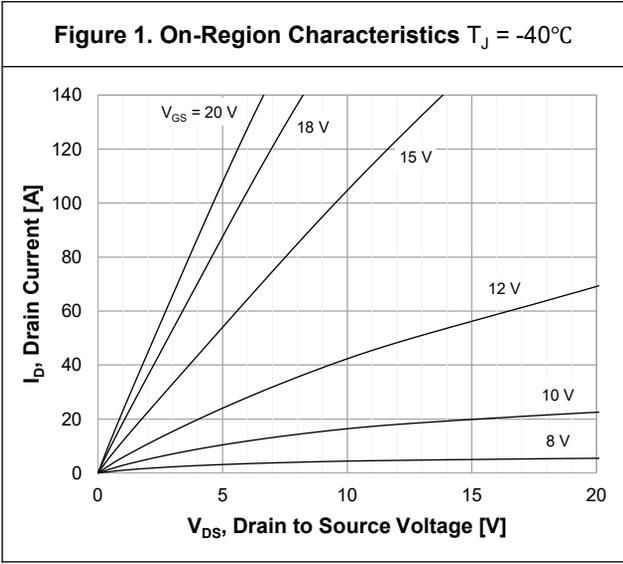
3. Body Diode

Electrical Characteristics ($T_C = 25^\circ\text{C}$ unless otherwise noted)

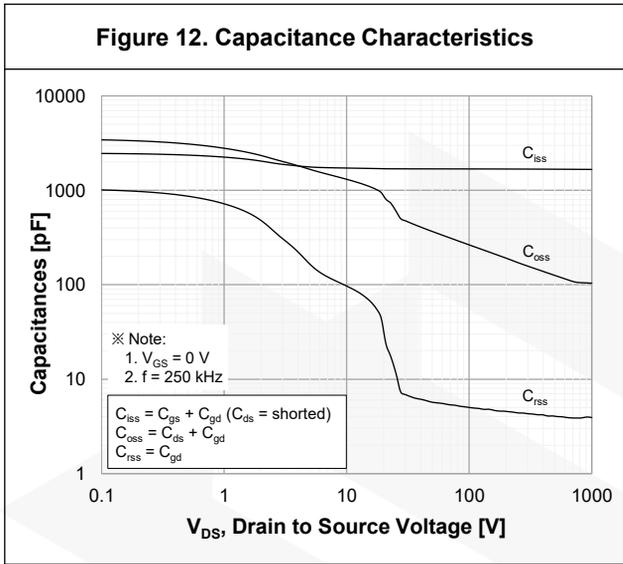
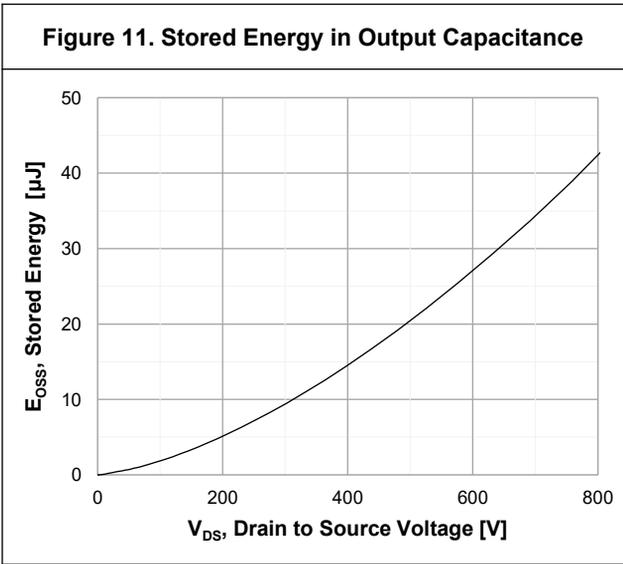
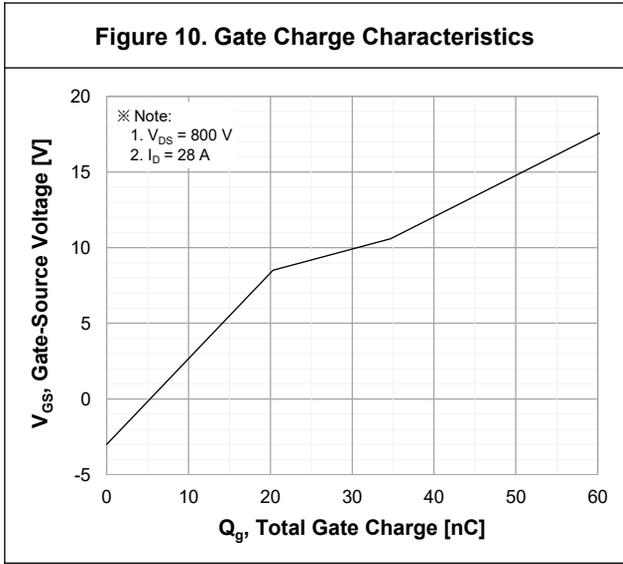
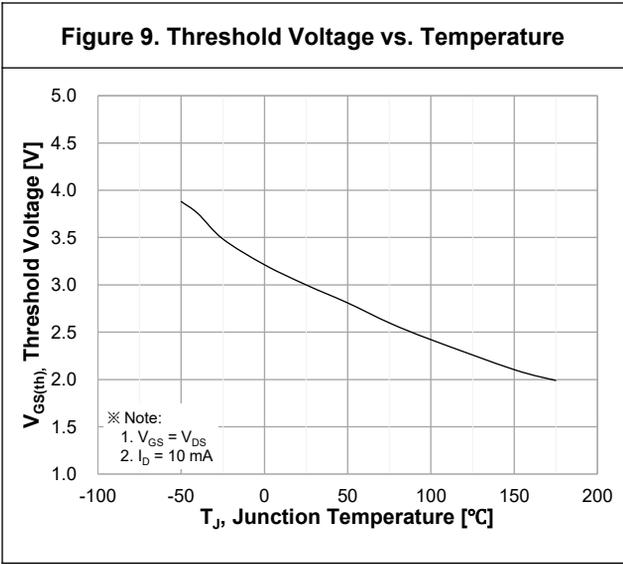
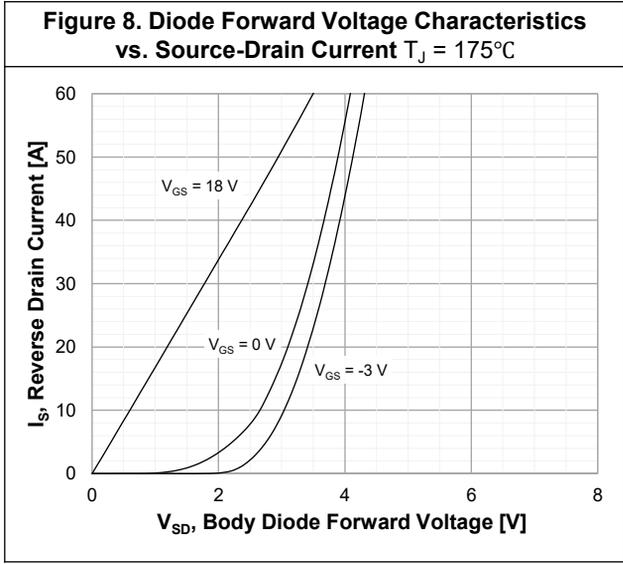
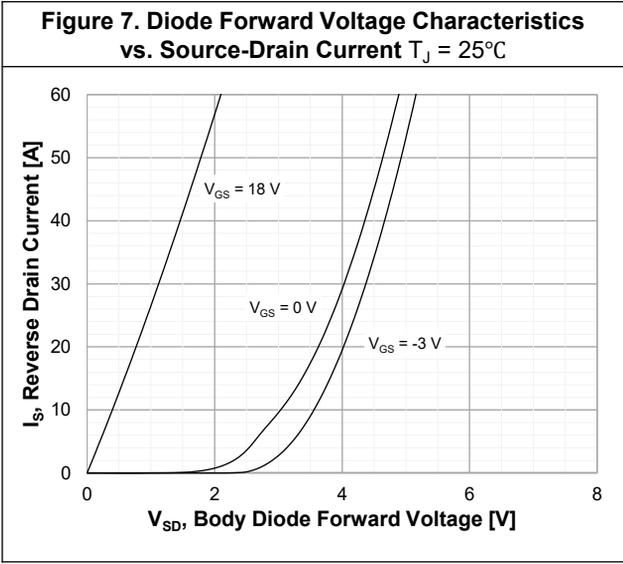
Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
Source-Drain Diode Characteristics						
I_S	Continuous Diode Forward Current	$V_{GS} = -3\text{ V}$			57*	A
I_{SM}	Pulsed Diode Forward Current	$V_{GS} = -3\text{ V}$ (Note1)			142*	
V_{SD}	Diode Forward Voltage	$V_{GS} = -3\text{ V}, I_{SD} = 28\text{ A}$		4.3		V
t_{rr}	Reverse Recovery Time	$V_{DD} = 800\text{ V}, I_{SD} = 28\text{ A},$ $di_F/dt = 3000\text{ A}/\mu\text{s}$		15		ns
Q_{rr}	Reverse Recovery Charge			219		nC
I_{rrm}	Peak Reverse Recovery Current			24		A

*Limited by maximum junction temperature.

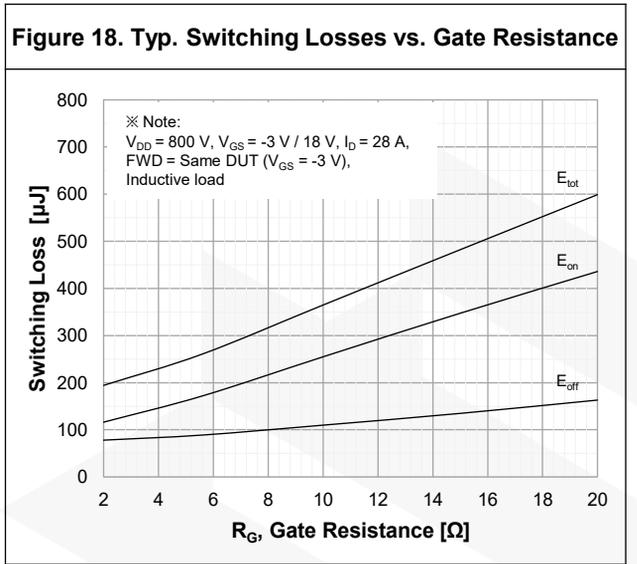
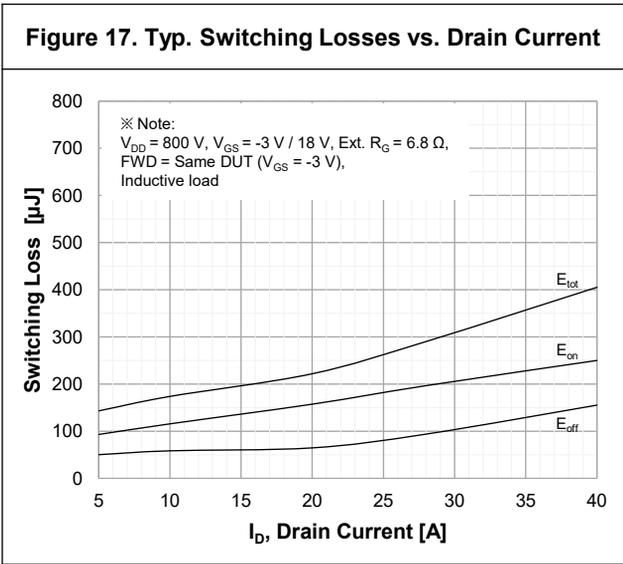
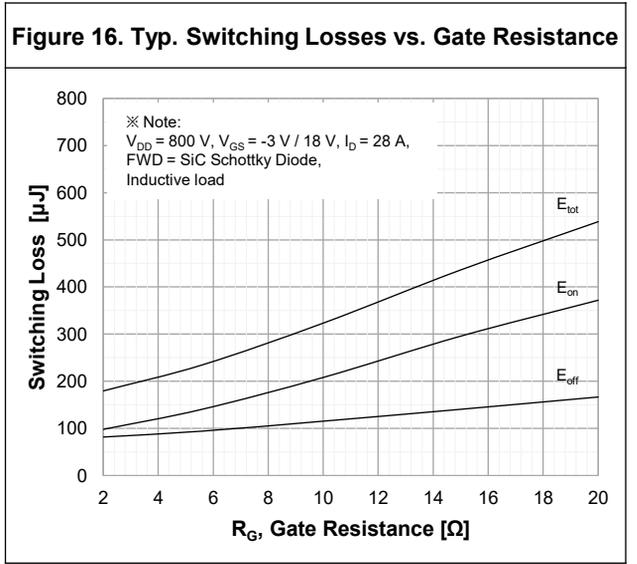
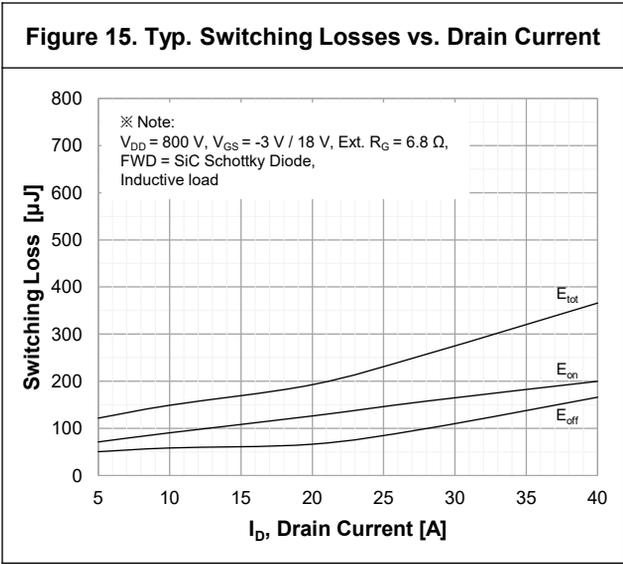
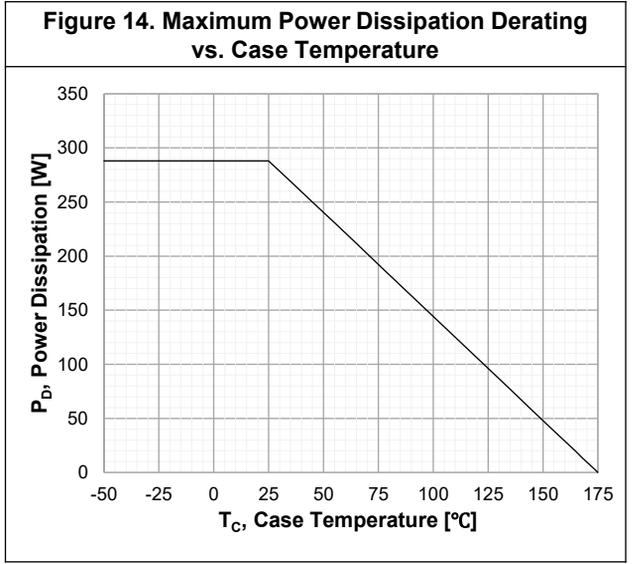
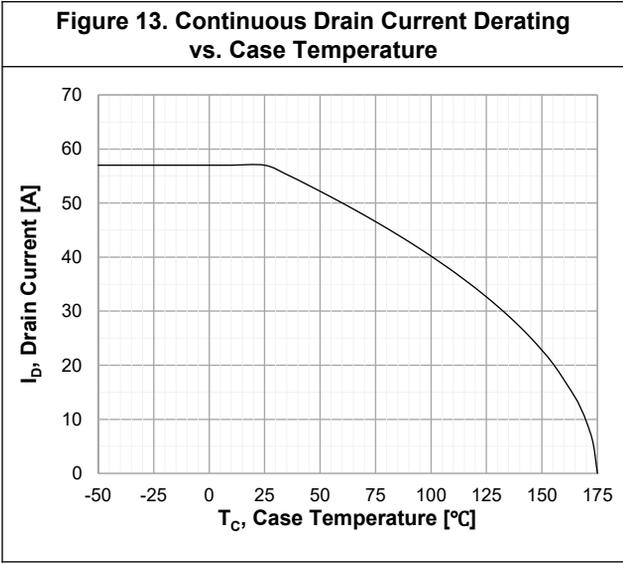
4. Typical Performance Characteristics



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4. Typical Performance Characteristics

Figure 19. Maximum Safe Operating Area

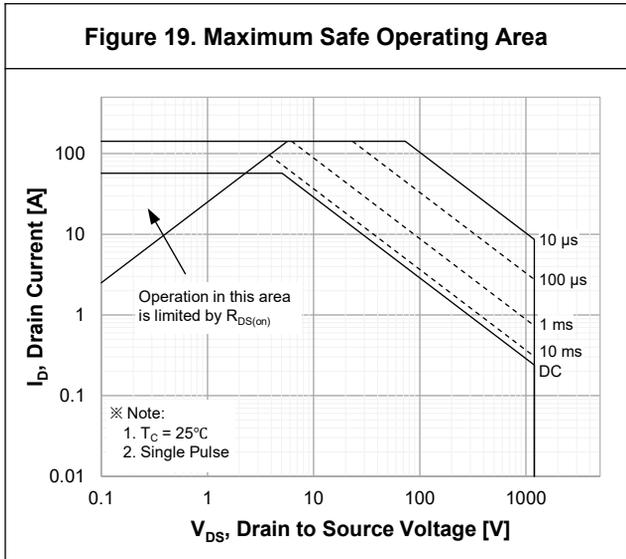
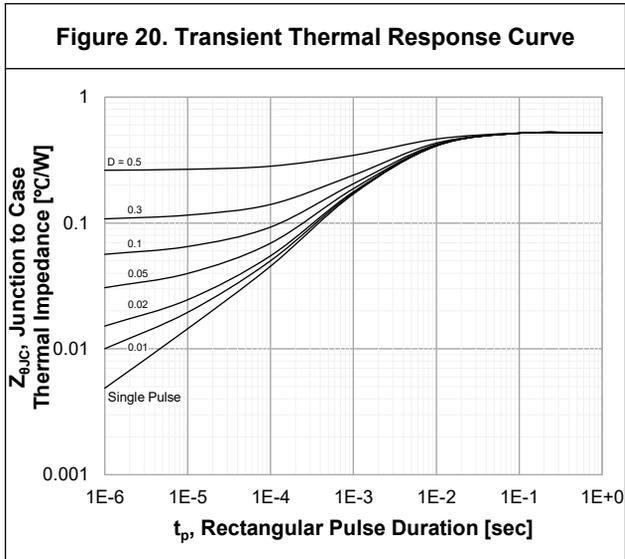


Figure 20. Transient Thermal Response Curve



5. Testing conditions

Figure 21. Inductive Load Switching Test Circuit and Waveforms

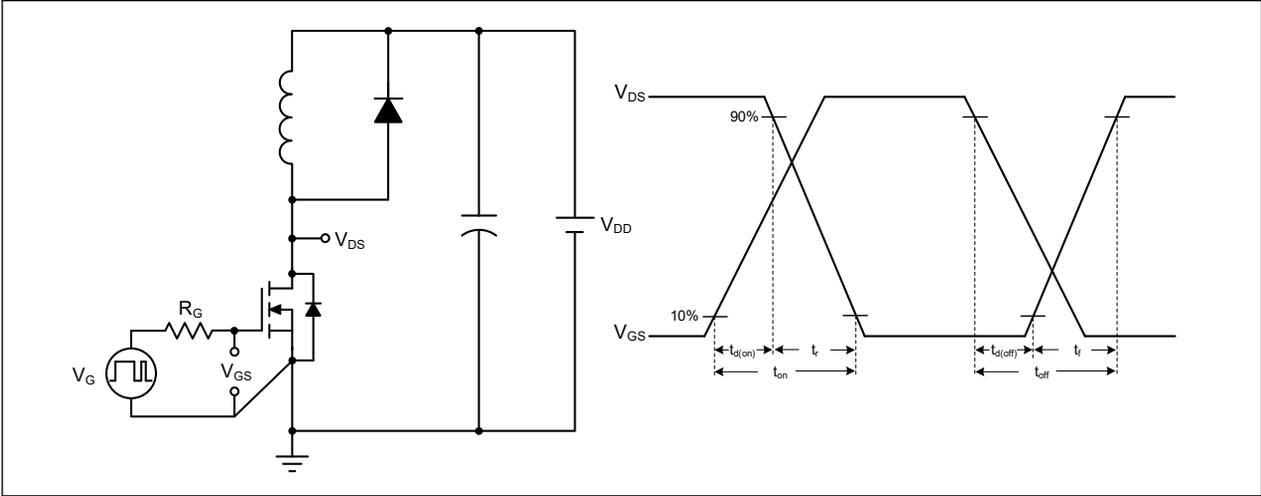
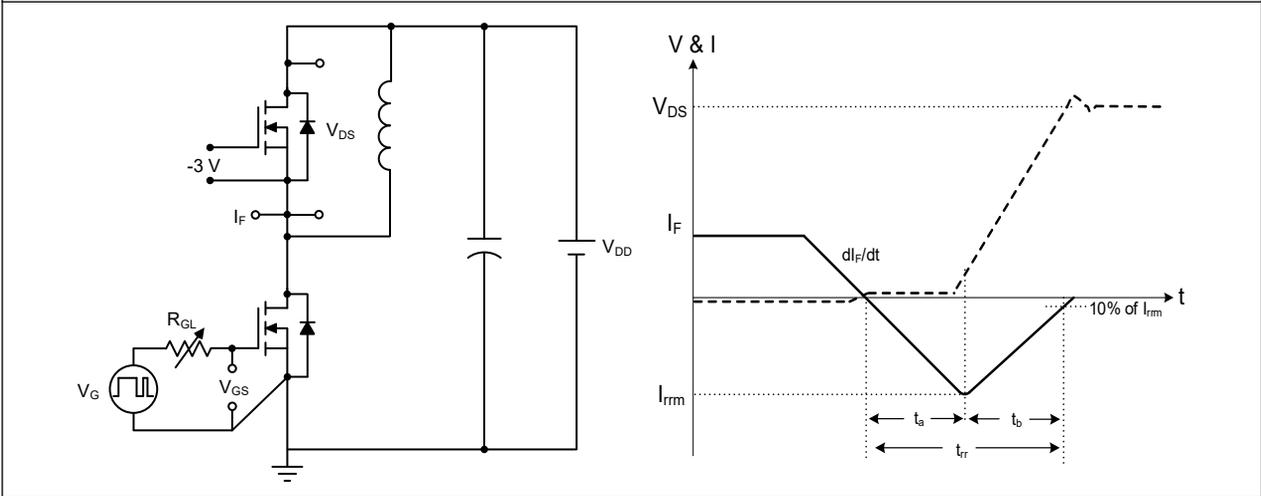
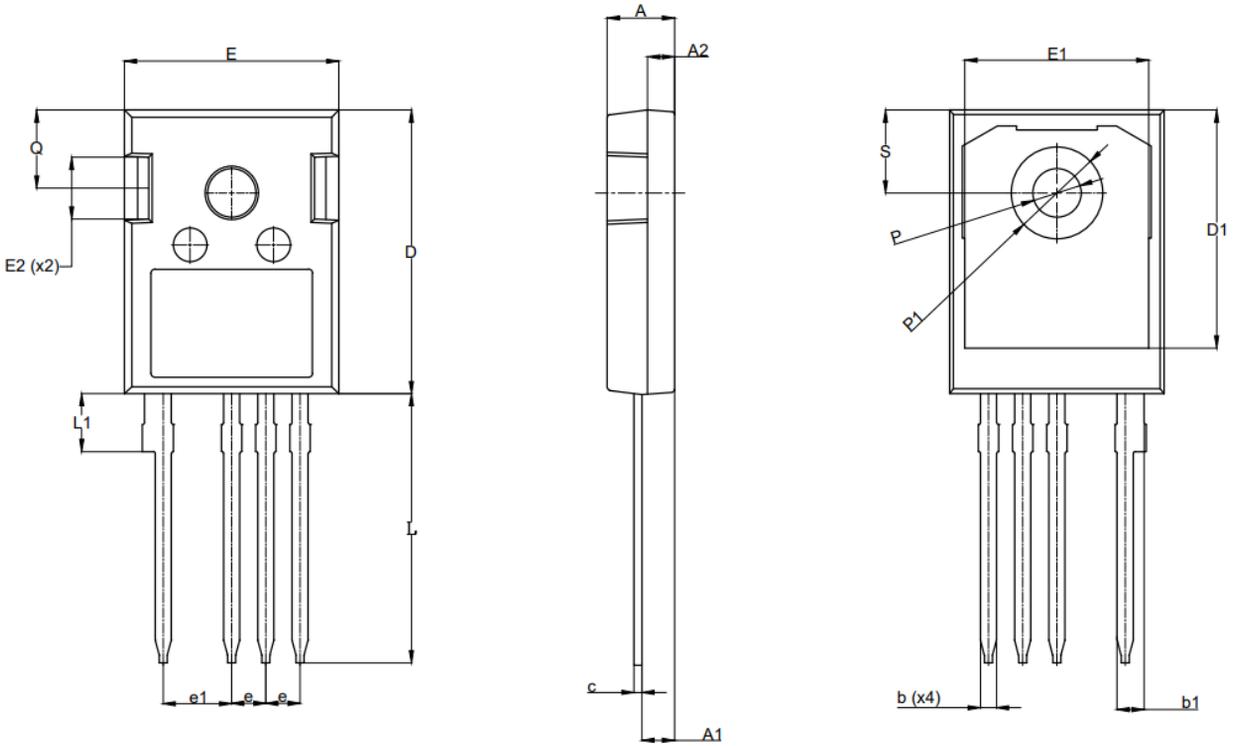


Figure 22. Peak Diode Recovery dv/dt Test Circuit and Waveforms



6. Package Outlines – TO-247-4L

* Dimensions in millimeters



SYMBOL	Common		
	DIMENSIONS MILLIMETER		
	MIN.	NOM.	MAX.
A	4.80	5.00	5.20
A1	2.29	2.42	2.54
A2	1.90	2.00	2.10
b	1.10	1.20	1.30
b1	1.86	2.01	2.15
c	0.50	0.60	0.70
D	20.90	21.00	21.10
D1	17.43	17.63	17.83
E	15.75	15.94	16.13
E1	13.46	13.66	13.86
E2	4.32	4.58	4.83
e	2.54 BSC.		
e1	5.08 BSC.		
L	19.80	19.95	20.10
L1	-	-	4.30
P	3.56	3.61	3.66
P1	6.75	6.80	6.85
Q	5.38	5.79	6.20
S	6.15 BSC.		